

IRF840B/IRFS840B

500V N-Channel MOSFET

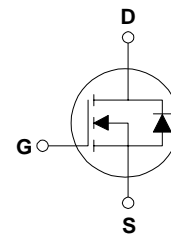
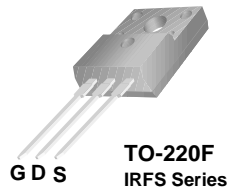
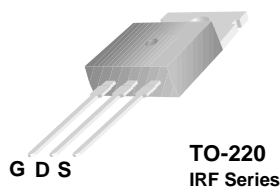
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies, power factor correction and electronic lamp ballasts based on half bridge.

Features

- 8.0A, 500V, $R_{DS(on)} = 0.8\Omega @ V_{GS} = 10V$
- Low gate charge (typical 41 nC)
- Low Crss (typical 35 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	IRF840B	IRFS840B	Units
V _{DSS}	Drain-Source Voltage	500		V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	8.0	8.0	A
		5.1	5.1	A
I _{DM}	Drain Current - Pulsed (Note 1)	32	32	A
V _{GSS}	Gate-Source Voltage	± 30		V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	320		mJ
I _{AR}	Avalanche Current (Note 1)	8.0		A
E _{AR}	Repetitive Avalanche Energy (Note 1)	13.4		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5		V/ns
P _D	Power Dissipation (T _C = 25°C) - Derate above 25°C	134	44	W
		1.08	0.35	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150		°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		°C

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	IRF840B	IRFS840B	Units
R _{θJC}	Thermal Resistance, Junction-to-Case Max.	0.93	2.86	°C/W
R _{θCS}	Thermal Resistance, Case-to-Sink Typ.	0.5	--	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient Max.	62.5	62.5	°C/W

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	500	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$, Referenced to 25°C	--	0.55	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	--	--	10	μA
		$V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$	--	--	100	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 4.0\text{ A}$	--	0.65	0.8	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 4.0\text{ A}$ (Note 4)	--	7.3	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	1400	1800	pF
C_{oss}	Output Capacitance		--	145	190	pF
C_{rss}	Reverse Transfer Capacitance		--	35	45	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 250\text{ V}, I_D = 8.0\text{ A},$ $R_G = 25\ \Omega$	--	22	55	ns
t_r	Turn-On Rise Time		--	65	140	ns
$t_{d(off)}$	Turn-Off Delay Time		--	125	260	ns
t_f	Turn-Off Fall Time		(Note 4, 5)	--	75	160
Q_g	Total Gate Charge	$V_{DS} = 400\text{ V}, I_D = 8.0\text{ A},$ $V_{GS} = 10\text{ V}$	--	41	53	nC
Q_{gs}	Gate-Source Charge		--	6.5	--	nC
Q_{gd}	Gate-Drain Charge		(Note 4, 5)	--	17	--

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	8.0	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	32	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 8.0\text{ A}$	--	--	1.4	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 8.0\text{ A},$	--	390	--	ns
Q_{rr}	Reverse Recovery Charge	$di_F / dt = 100\text{ A}/\mu\text{s}$ (Note 4)	--	4.2	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 9.0\text{ mH}, I_{AS} = 8.0\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 8.0\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\ \mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

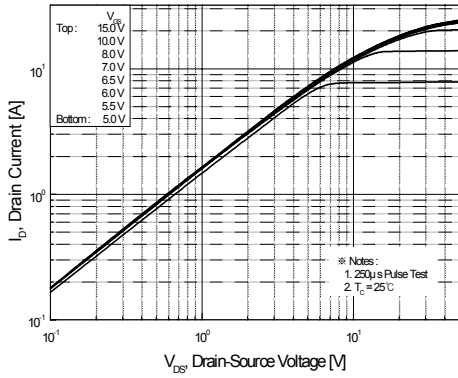


Figure 1. On-Region Characteristics

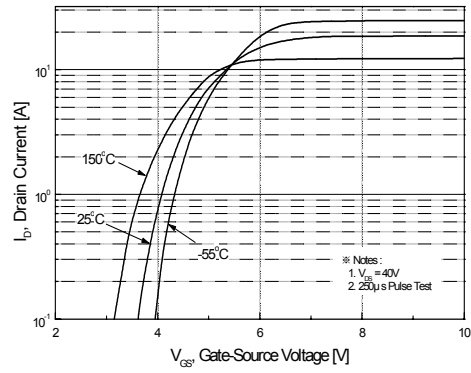


Figure 2. Transfer Characteristics

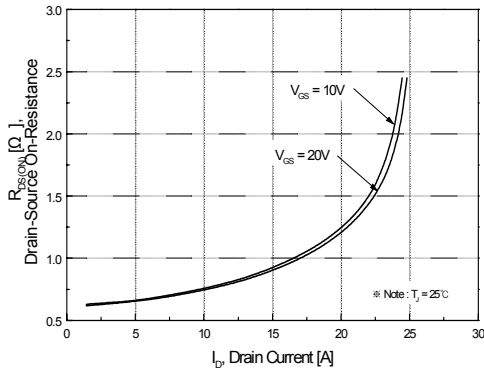


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

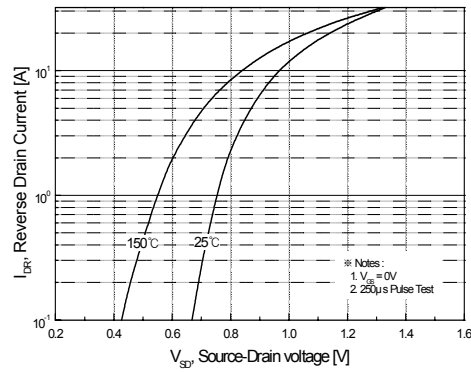


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

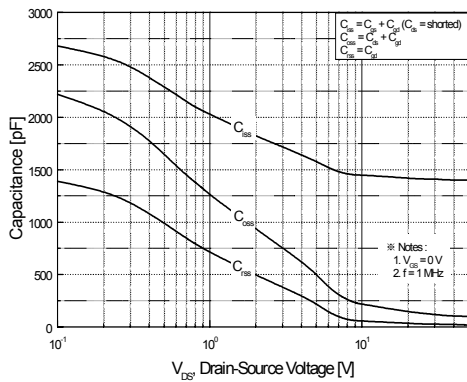


Figure 5. Capacitance Characteristics

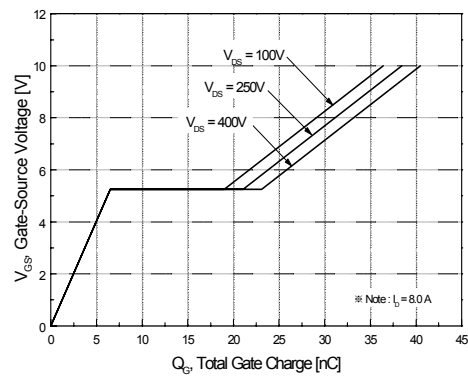


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

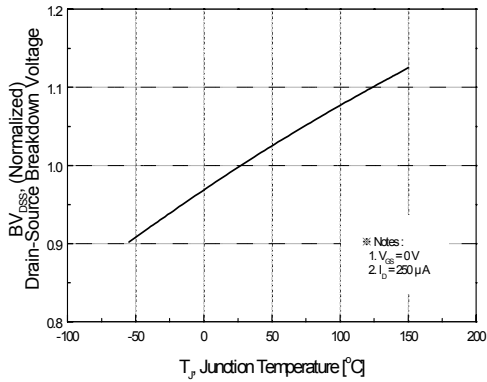


Figure 7. Breakdown Voltage Variation vs Temperature

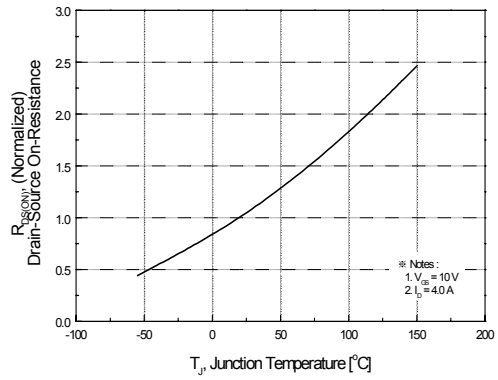


Figure 8. On-Resistance Variation vs Temperature

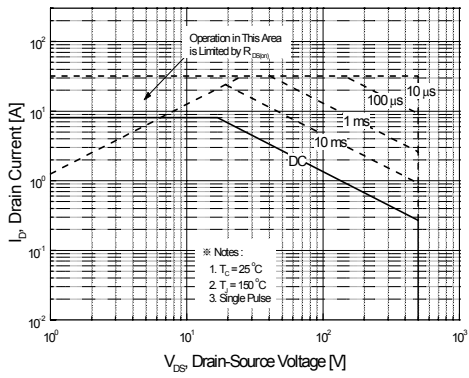


Figure 9-1. Maximum Safe Operating Area for IRF840B

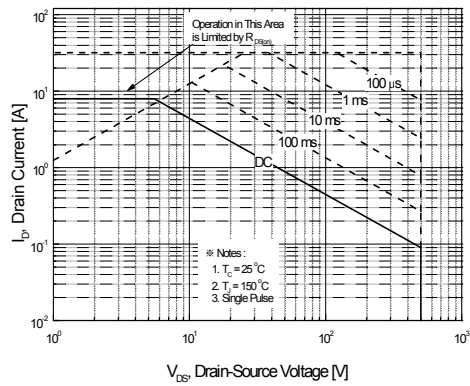


Figure 9-2. Maximum Safe Operating Area for IRFS840B

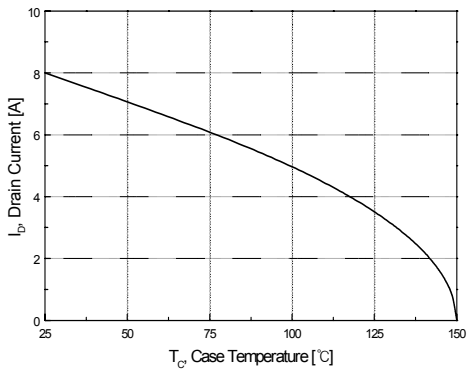


Figure 10. Maximum Drain Current vs Case Temperature

Typical Characteristics (Continued)

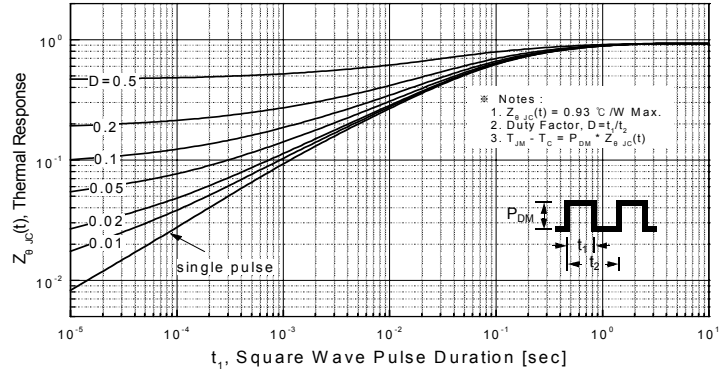


Figure 11-1. Transient Thermal Response Curve for IRF840B

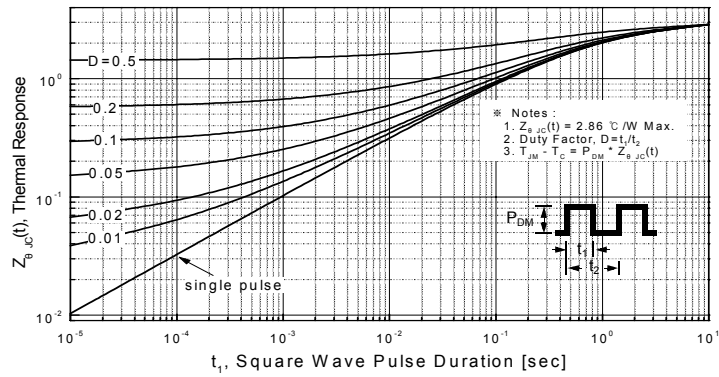
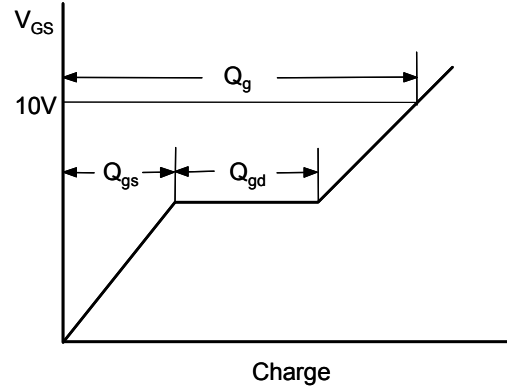
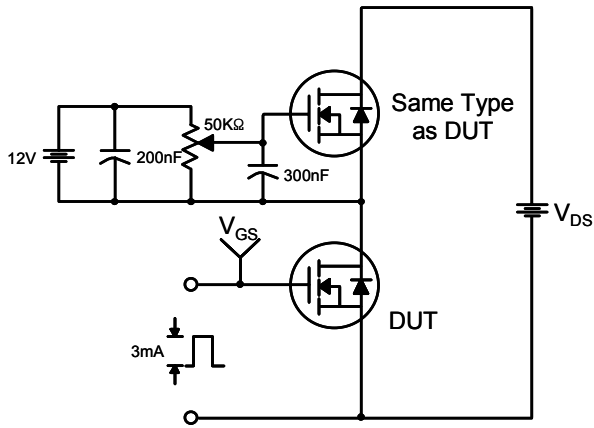
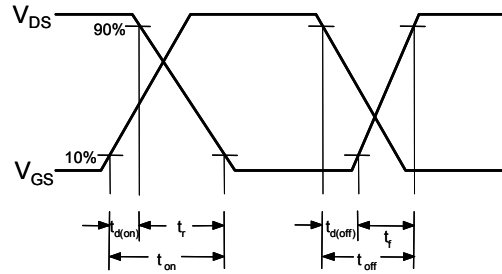
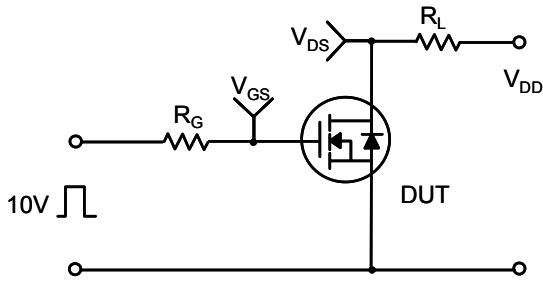


Figure 11-2. Transient Thermal Response Curve for IRFS840B

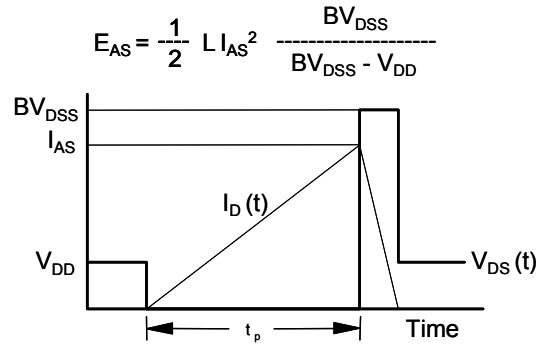
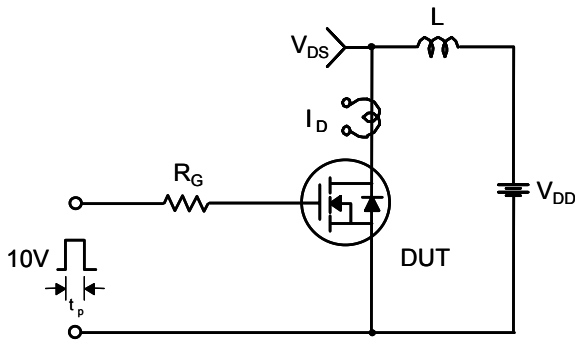
Gate Charge Test Circuit & Waveform



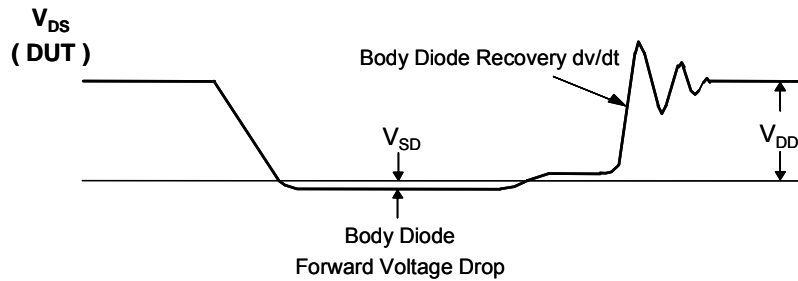
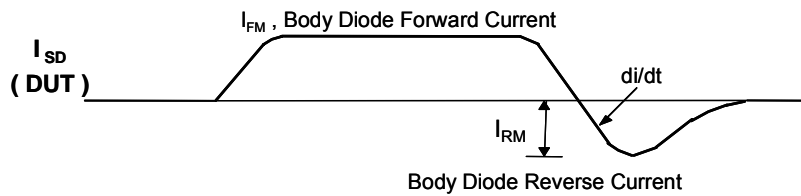
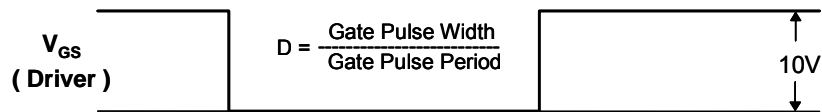
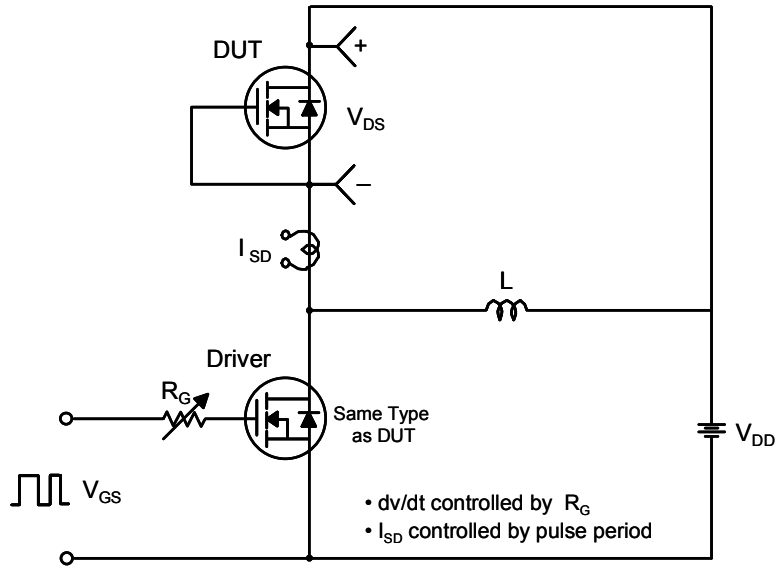
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



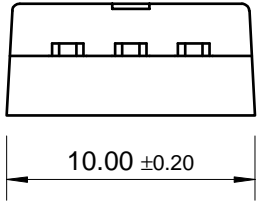
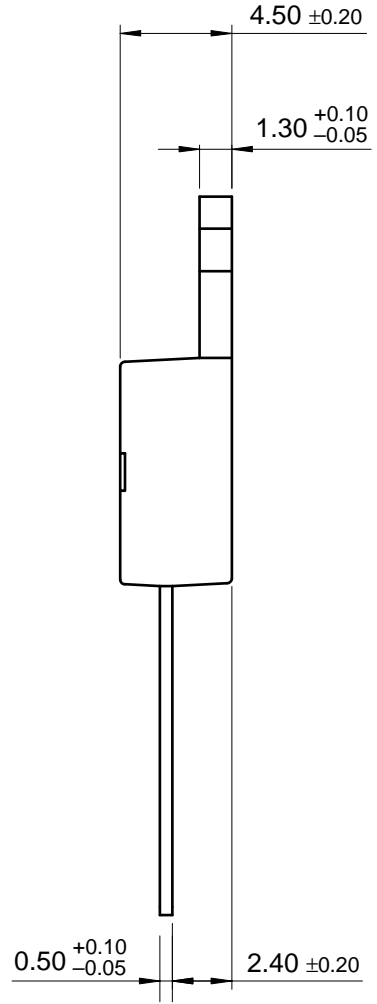
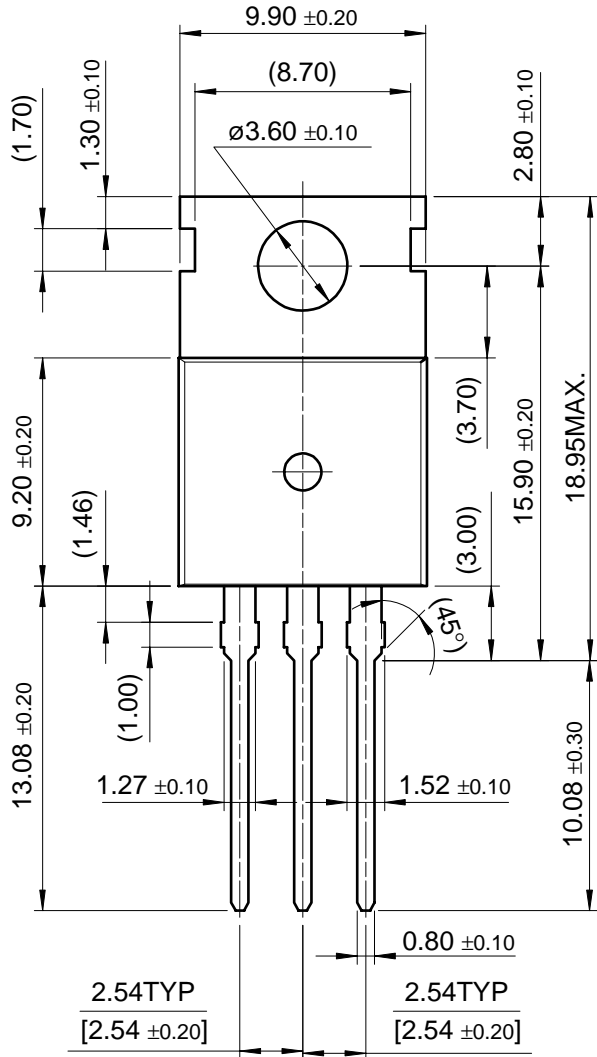
Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimensions

TO-220

IRF840B/IRFS840B



Dimensions in Millimeters

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE _x [™]	FAST [®]	IntelliMAX [™]	POP [™]	SPM [™]
ActiveArray [™]	FAST _r [™]	ISOPLANAR [™]	Power247 [™]	Stealth [™]
Bottomless [™]	FPS [™]	LittleFET [™]	PowerEdge [™]	SuperFET [™]
CoolFET [™]	FRFET [™]	MICROCOUPLER [™]	PowerSaver [™]	SuperSOT [™] -3
CROSSVOLT [™]	GlobalOptoisolator [™]	MicroFET [™]	PowerTrench [®]	SuperSOT [™] -6
DO _{ME} [™]	GTO [™]	MicroPak [™]	QFET [®]	SuperSOT [™] -8
EcoSPARK [™]	HiSeC [™]	MICROWIRE [™]	QS [™]	SyncFET [™]
E ² CMOS [™]	I ² C [™]	MSX [™]	QT Optoelectronics [™]	TinyLogic [®]
EnSigna [™]	<i>i-Lo</i> [™]	MSXPro [™]	Quiet Series [™]	TINYOPTO [™]
FACT [™]	ImpliedDisconnect [™]	OCX [™]	RapidConfigure [™]	TruTranslation [™]
FACT Quiet Series [™]		OCXPro [™]	RapidConnect [™]	UHC [™]
Across the board. Around the world. [™]		OPTOLOGIC [®]	μSerDes [™]	UltraFET [®]
The Power Franchise [®]		OPTOPLANAR [™]	SILENT SWITCHER [®]	UniFET [™]
Programmable Active Droop [™]		PACMAN [™]	SMART START [™]	VCX [™]

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.